

AMENDMENTS TO THE CLAIMS:

This listing of claims will replace all prior versions, and listings, of claims in the application:

LISTING OF CLAIMS:

1. (Currently Amended) A slurry for cutting a silicon ingot, comprising abrasive grains and a basic material, ~~characterized in that~~ wherein:
the basic material is alkaline metal hydroxide, alkaline earth hydroxide or mixtures thereof;
a content of the basic material is at least 3.5% by mass based on a total mass of a liquid component of the slurry;
the slurry contains organic amine in a mass ratio of 0.5 to 5.0 with respect to water in the liquid component of the slurry; and
pH of the slurry is 12 or more.
2. (Currently Amended) A method of cutting a silicon ingot using a slurry for cutting a silicon ingot, comprising abrasive grains and a basic material, ~~characterized in that~~ wherein:
the basic material is alkaline metal hydroxide, alkaline earth hydroxide or mixtures thereof;
a content of the basic material is at least 3.5% by mass based on a total mass of a liquid component of the slurry;
the slurry contains organic amine in a mass ratio of 0.5 to 5.0 with respect to water in the liquid component of the slurry;

pH of the slurry is 12 or more; and
the slurry is used at 65°C to 95°C.